

2MBI300VH-120-50

IGBT Modules

Power Module (V series)
1200V / 300A / 2-in-1 package

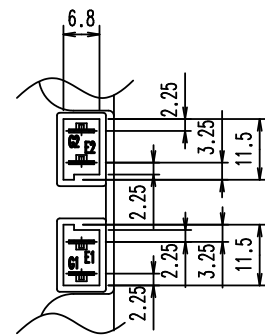
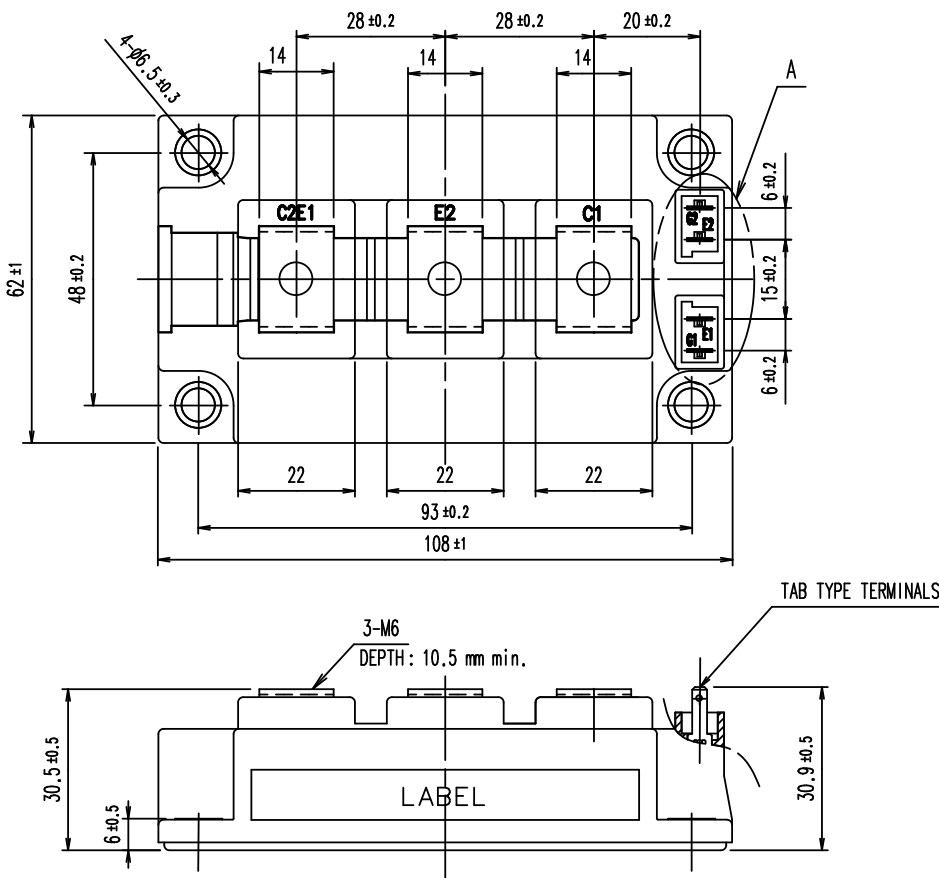
■ **Features**

- AC-switch
- High speed switching
- Voltage drive
- Low Inductance module structure

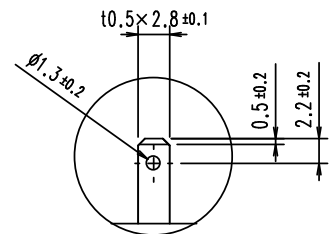
■ **Applications**

AC-switch for UPS, PCS and etc.

■ **Outline drawing (Unit : mm)**



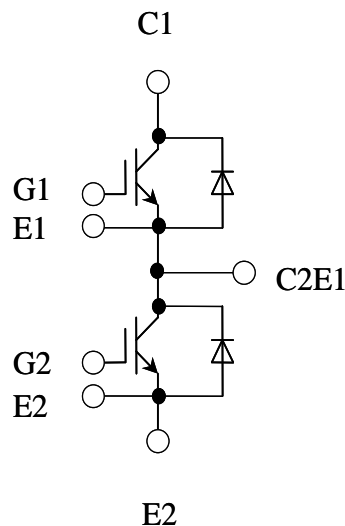
DETAIL A



DETAIL TAB TYPE TERMINALS

Weight: 370g (typ.)

■ **Equivalent circuit**



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■ Absolute maximum ratings (at $T_C = 25^\circ\text{C}$ unless otherwise specified)

Items		Symbols	Conditions	Maximum ratings	Units	
Collector-Emitter voltage		V_{CES}		1200	V	
Gate-Emitter voltage		V_{GES}		± 20	V	
Collector current	I_C		Continuous	$T_C = 100^\circ\text{C}$	300	A
				$T_C = 25^\circ\text{C}$	360	
	I_C pulse	1ms		600		
	$-I_C$			300		
	$-I_C$ pulse		1ms		600	
Collector power dissipation		P_C	1 device	1600	W	
Junction temperature		T_j		175	°C	
Operating junction temperature (under switching conditions)		T_{jop}		150		
Case temperature		T_C		125		
Storage temperature		T_{stg}		-40 ~ 125		
Isolation voltage	Between terminal and copper base (*1)	V_{iso}	AC: 1min.	4000	VAC	
Screw torque	Mounting	-	M5 or M6	3.0~6.0	N m	
	Terminals	-	M6	2.5~5.0		

(*1) All terminals should be connected together during the test.

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■ Electrical characteristics (at $T_j=25^\circ\text{C}$ unless otherwise specified)

NOTICE:

The external gate resistance (R_g) shown below is one of our recommend value for the purpose of minimum switching loss. However the optimum R_g depends on circuit configuration and/or environment. We recommend that the R_g has to be carefully chosen based on consideration if IGBT module matches design criteria, for example, switching loss, EMC/EMI, spike voltage, surge current and no unexpected oscillation and so on.

Items	Symbols	Conditions	Characteristics			Units	
			min.	typ.	max.		
Zero gate voltage collector current	I_{CES}	$V_{GE}=0V, V_{CE}=1200V$	-	-	2.0	mA	
Gate-Emitter leakage current	I_{GES}	$V_{CE}=0V, V_{GE}=\pm 20V$	-	-	400	nA	
Gate-Emitter threshold voltage	$V_{GE(th)}$	$V_{CE}=20V, I_C=300mA$	6.0	6.5	7.0	V	
Collector-Emitter saturation voltage	$V_{CE(sat)}$ (terminal)	$V_{GE}=15V, I_C=300A$	$T_j=25^\circ\text{C}$	-	1.95	2.40	V
			$T_j=125^\circ\text{C}$	-	2.25	-	
			$T_j=150^\circ\text{C}$	-	2.30	-	
	$V_{CE(sat)}$ (chip)	$V_{GE}=15V, I_C=300A$	$T_j=25^\circ\text{C}$	-	1.75	2.10	
			$T_j=125^\circ\text{C}$	-	2.05	-	
Internal gate resistance	$R_{g(int)}$	-	-	2.5	-	Ω	
Input capacitance	C_{ies}	$V_{CE}=10V, V_{GE}=0V, f=1\text{MHz}$	-	24.1	-	nF	
Turn-on time	t_{on}	$V_{CC}=600V, I_C=300A, V_{GE}=\pm 15V, R_g=1.8\Omega, T_j=150^\circ\text{C}, L_s=30\text{nH}$	-	600	-	nsec	
	t_r		-	200	-		
	$t_{r(l)}$		-	50	-		
Turn-off time	t_{off}		-	800	-		
	t_f		-	80	-		
Forward on voltage	V_F (terminal)	$V_{GE}=0V, I_F=300A$	$T_j=25^\circ\text{C}$	-	1.90	2.35	V
			$T_j=125^\circ\text{C}$	-	2.05	-	
			$T_j=150^\circ\text{C}$	-	2.00	-	
	V_F (chip)	$V_{GE}=0V, I_F=300A$	$T_j=25^\circ\text{C}$	-	1.70	2.15	
			$T_j=125^\circ\text{C}$	-	1.85	-	
Reverse recovery time	t_{rr}	$I_F=300A$	-	150	-	nsec	

■ Thermal resistance characteristics

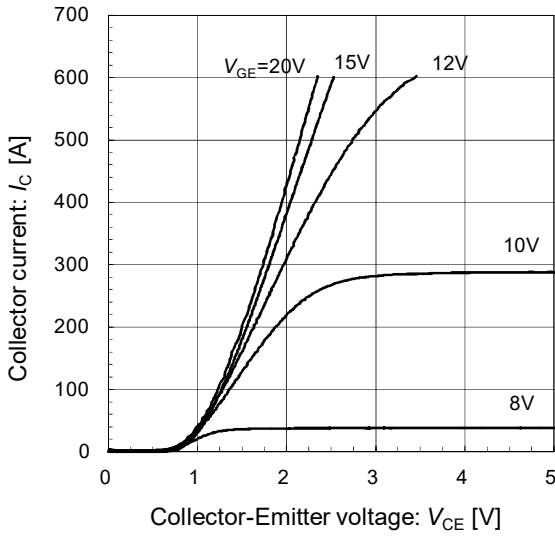
Items	Symbols	Conditions	Characteristics			Units
			min.	typ.	max.	
Thermal resistance (1device)	$R_{th(j-c)}$	IGBT	-	-	0.093	$^\circ\text{C/W}$
		FWD	-	-	0.150	
Contact thermal resistance (1device) (*1)	$R_{th(c-f)}$	with thermal compound	-	0.0125	-	

(*1) This is the value which is defined mounting on the additional cooling fin with thermal compound.

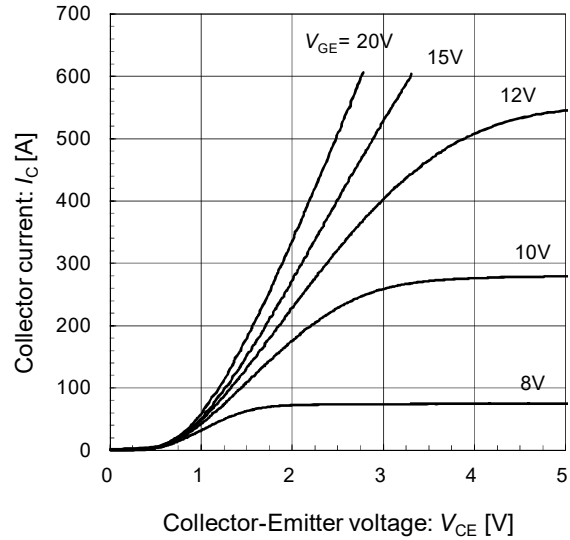
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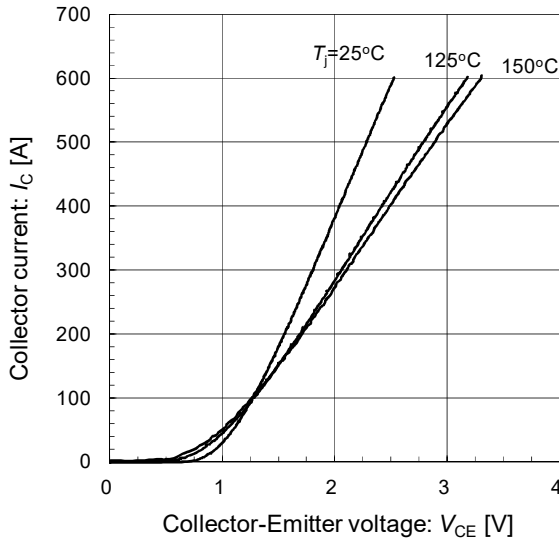
Collector current vs. Collector-Emitter voltage (typ.)
 $T_j = 25^\circ\text{C}$ / chip



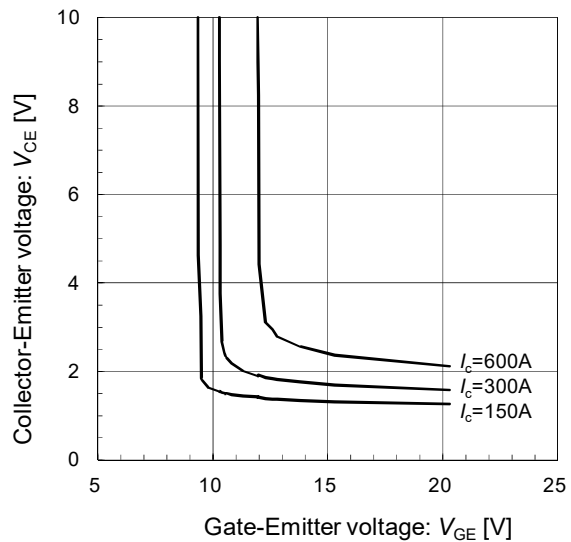
Collector current vs. Collector-Emitter voltage (typ.)
 $T_j = 150^\circ\text{C}$ / chip



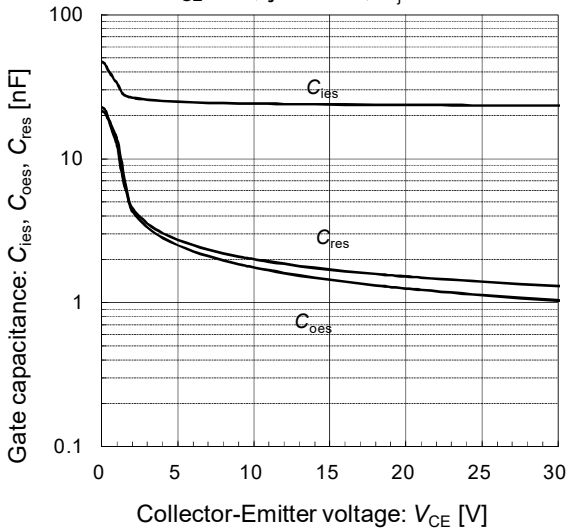
Collector current vs. Collector-Emitter voltage (typ.)
 $V_{GE} = 15\text{V}$ / chip



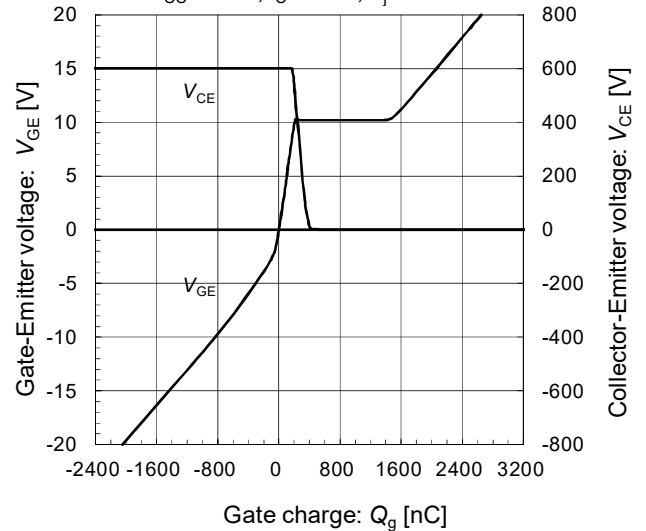
Collector-Emitter voltage vs. Gate-Emitter voltage (typ.)
 $T_j = 25^\circ\text{C}$ / chip



Gate capacitance vs. Collector-Emitter voltage (typ.)
 $V_{GE} = 0\text{V}$, $f = 1\text{MHz}$, $T_j = 25^\circ\text{C}$

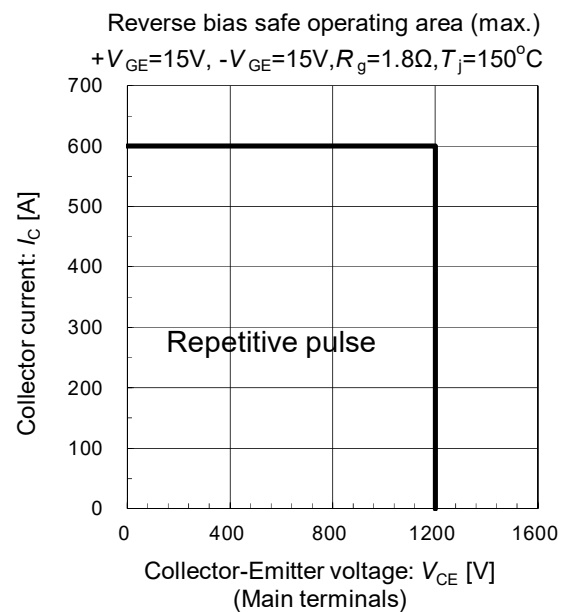
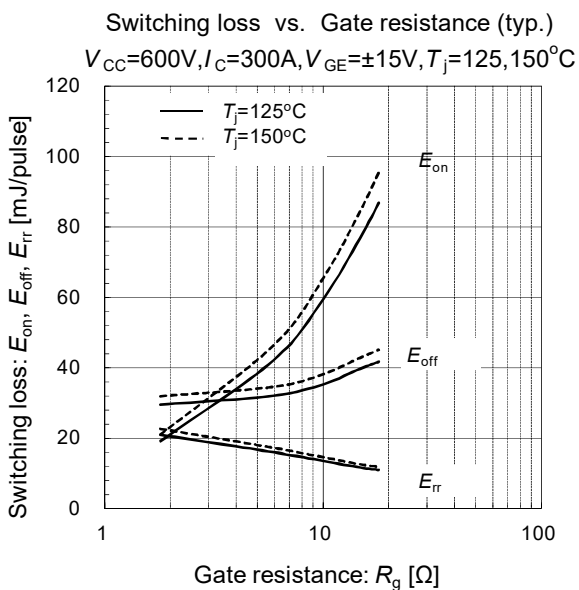
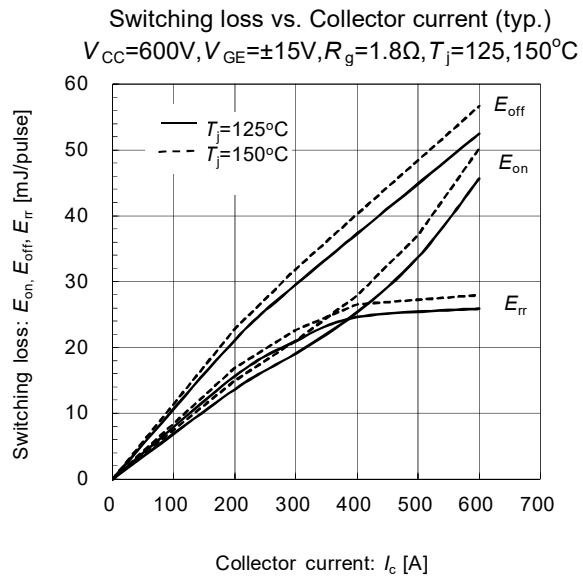
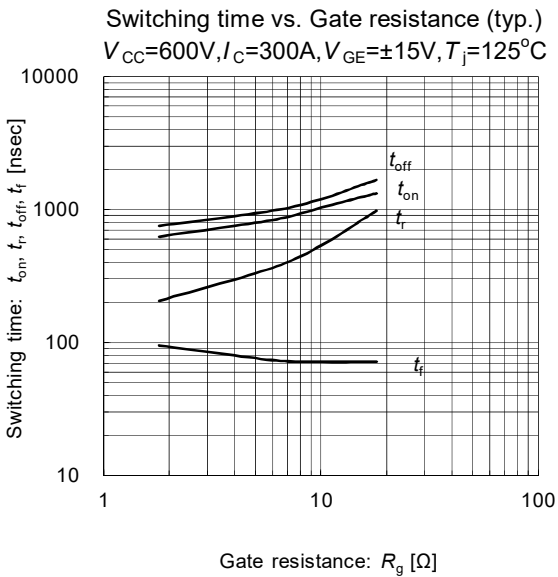
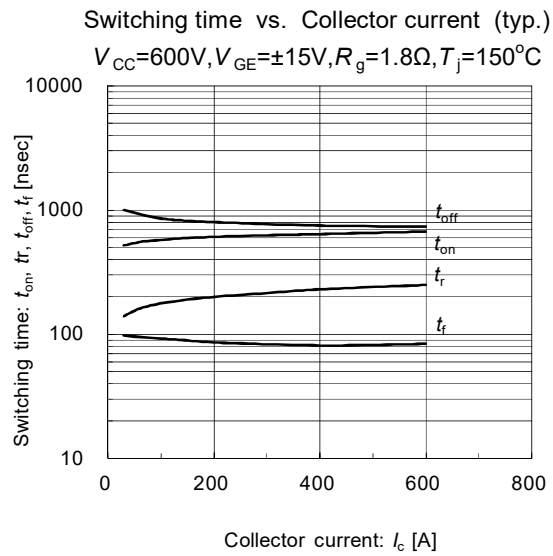
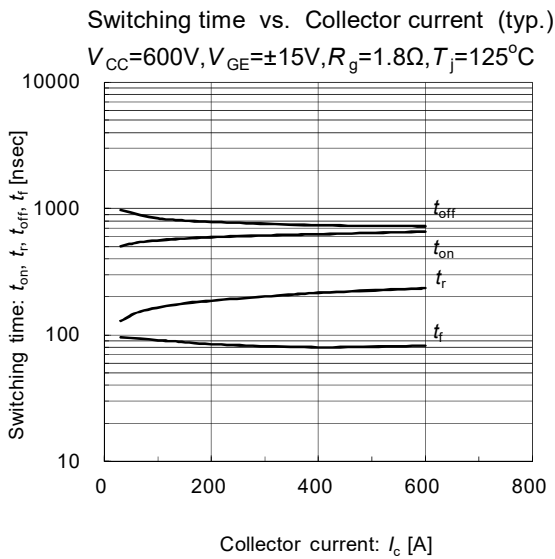


Dynamic gate charge (typ.)
 $V_{CC} = 600\text{V}$, $I_C = 300\text{A}$, $T_j = 25^\circ\text{C}$



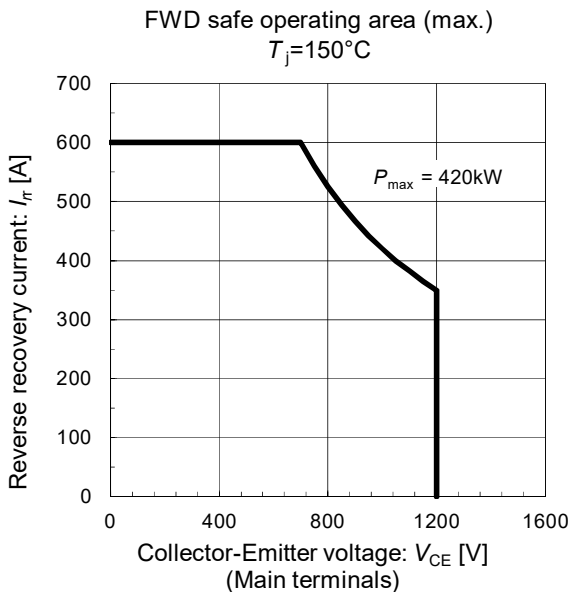
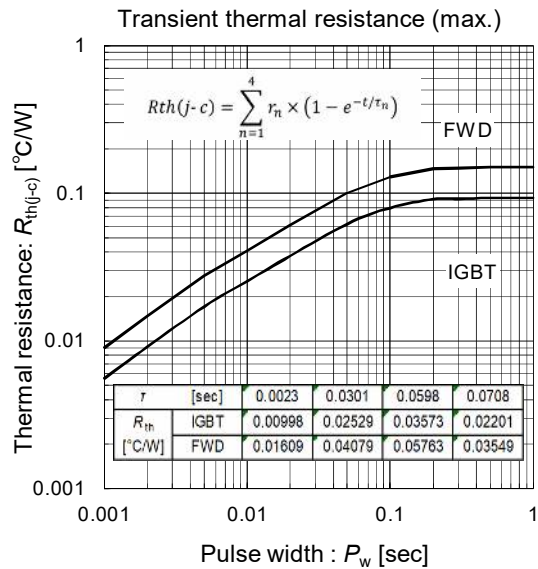
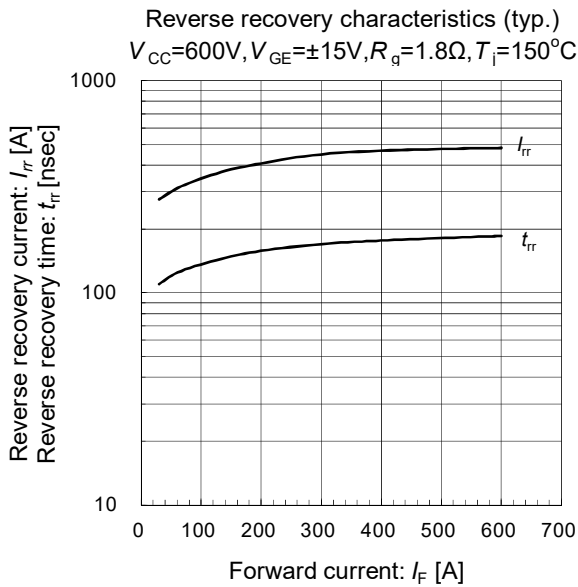
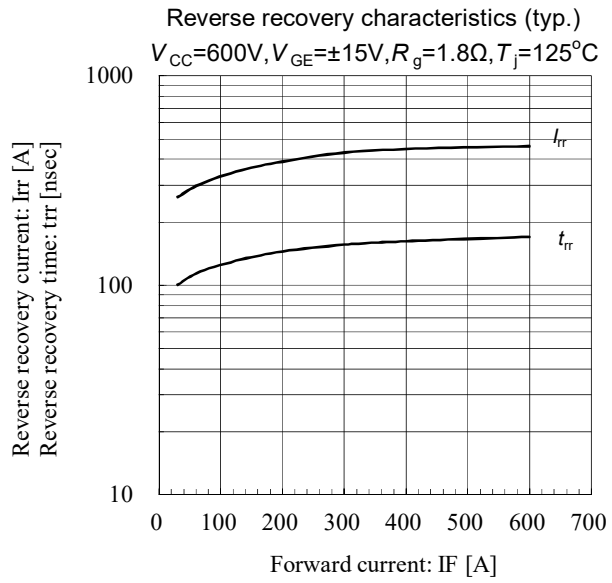
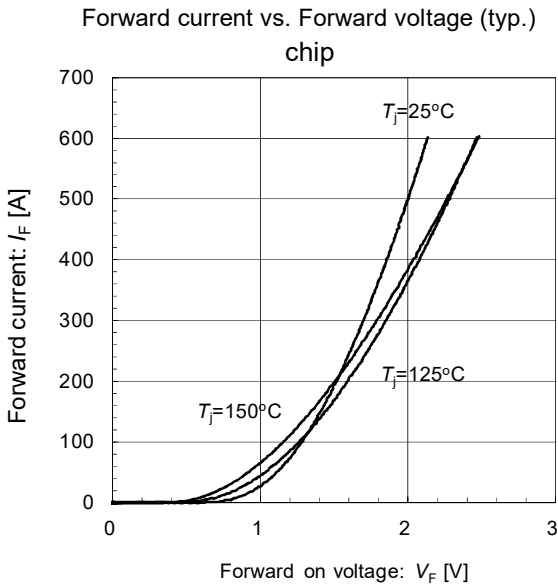
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